

POH - AB L3&L4 Flex Cable v1.1.2 - 2-layer Flex-Rigid Board

Material Selection

Polyimide  
Permittivity @ 100MHz:  
Permittivity @ 1GHz:  
Loss Tangent @ 100MHz:  
Loss Tangent @ 1GHz:  
Lead Free Assembly Compatible

Non-standard Tolerances

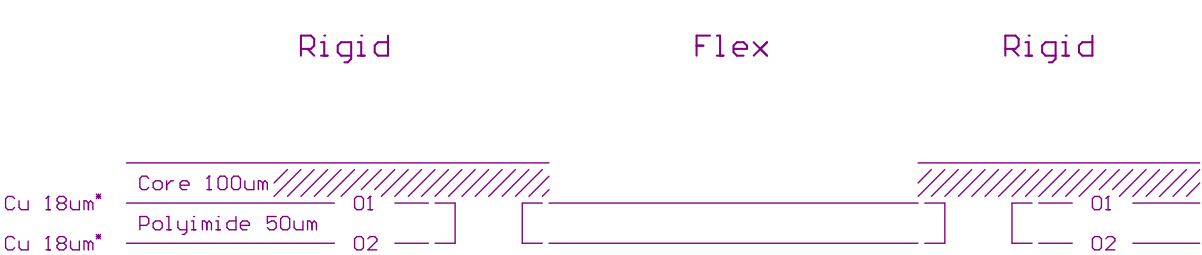
Holes sized 0.2mm may be plugged by plating. These are all vias.  
For them we do not care the finished hole sizes.

Solder resist colour: green  
Silkscreen print colour: white

Surface Finish

On top and bottom layer surfaces:  
electroless nickel immersion gold

Board Layer Stack / Drill Layer-Pairs



Layer Name Gerber

Top Overlay	.gto
Top Solder Mask	.gts
GND	.g1
Signal Layer	.gbl
Bottom Solder Mask	.gbs
Bottom Overlay	.gbo
Board Outline	.gm1

Holes / Drilling

Drill files contain finished hole diameters  
Drilling layer pairs: 1-2

\*35um final after plating  
Total Laminated Thickness on Rigid Region: 0.3mm +/- 0.05mm !

Board Outline

Contour routed with break-away tabs

Element Counts

(for reference only)

Nets: 58  
Pads: 128  
Tracks: 462  
Polygons: 1  
Holes: 8  
Vias: 8

Controlled Impedance Reference

Diff. trace width/space on bottom layer (microstrip) 60 ohms +/- 10% : 0.15/0.1mm